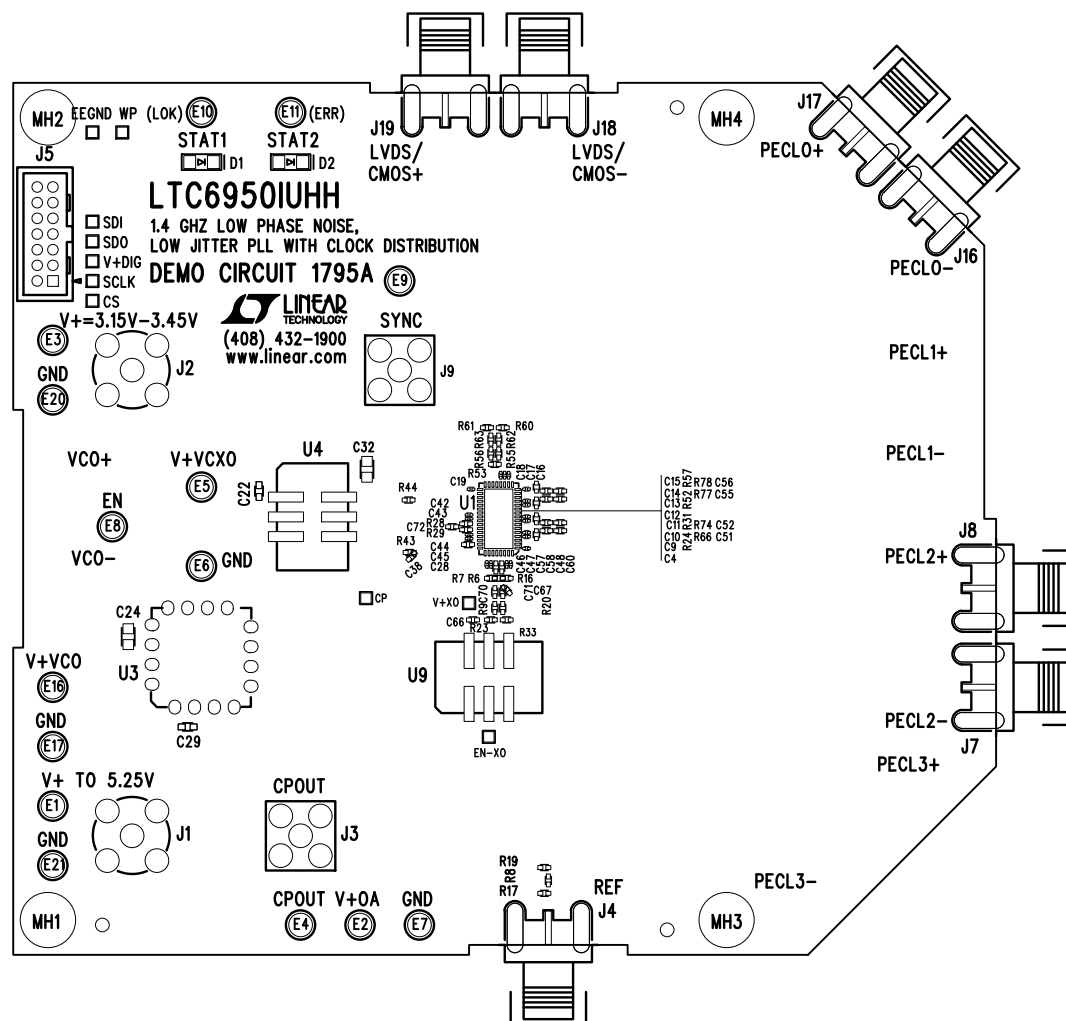
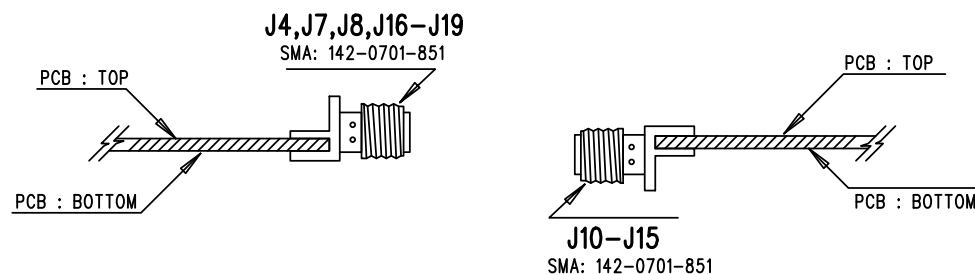
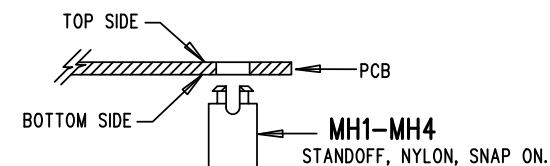



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	2ND PROTOTYPE	MICHEL A.	03-18-13



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	KIM T.	TITLE: TOP ASSEMBLY DRAWING 1.4 GHZ LOW PHASE NOISE, LOW JITTER PLL WITH CLOCK DISTRIBUTION		
APP ENG.	MICHEL A.			
SIZE	IC NO.	LTC6950IUHH	REV.	
N/A	DEMO CIRCUIT 1795A		2	
SCALE = NONE		FILENAME: DC1795A-2.PCB		SHT 1 OF 2